

**Remarks**

Favorable reconsideration of this application, in view of the above amendments and in light of the following remarks and discussion, is respectfully requested.

Applicants respectfully request entry of this response, as the response places the application in clear condition for allowance. Specifically, Applicants have amended the claims in view of a discussion with the Examiner.

Claims 1-10 and 16-22 are currently pending in the application; Claims 1, 3, 4, 6, 8, 16, 17, and 22 having been amended, and Claim 11 having been canceled without prejudice or disclaimer, by way of the present response. Applicants respectfully assert that support for the changes to the claims is self-evident from the originally filed disclosure, including the original claims, and that therefore no new matter has been added.

In the Office Action Claims 17-22 were rejected under 35 U.S.C. § 112, first paragraph; Claims 1-11 and 16-22 were rejected under 35 U.S.C. § 112, second paragraph; Claims 1, 2, 4, 6, 7, 10, 11, and 16-22 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Howell in view of Takigami; and Claims 1-11 and 16-22 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Sherman in view of Takigami.

Initially, Applicants express thanks for the courtesies extended by Examiner Thai to Applicants' representatives during a personal interview on December 7, 2004. Applicants respectfully assert that the following, with the Interview Summary prepared by the Examiner at the conclusion of the interview, includes the substance of the interview in accordance with MPEP § 713.04.

As stated above Claims 17-22 were rejected under 35 U.S.C. § 112, first paragraph. In response, Applicants have amended Claim 17 to recite "a semiconductor device comprising at least one semiconductor land . . . [and] a board comprising at least one board land electrically connected to the at least one semiconductor land," which Examiner Thai

agreed would overcome the rejection. Thus, Applicants respectfully request that the rejection of Claims 17-22 under 35 U.S.C. § 112, first paragraph, be withdrawn.

As stated above Claims 1-11 and 16-22 were rejected under 35 U.S.C. § 112, second paragraph. In response, Applicants have amended independent Claims 1 and 16 to recite “a semiconductor device comprising first lands electrically connected to second lands of a board,” and Claim 17 to recite “a semiconductor device comprising at least one semiconductor land . . . [and] a board comprising at least one board land electrically connected to the at least one semiconductor land” as stated above, which Examiner Thai agreed would overcome the rejection. Thus, Applicants respectfully request that the rejection of remaining Claims 1-10 and 16-22 under 35 U.S.C. § 112, second paragraph, be withdrawn.

Applicants respectfully assert that the above discussed changes to the claims are believed to overcome the rejections under 35 U.S.C. § 112, first and second paragraphs, as discussed during the interview. Applicants respectfully request that the Examiner contact the undersigned representative in the event that further changes to the claims are suggested by the Examiner.

As stated above Claims 1, 2, 4, 6, 7, 10, 11, and 16-22 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Howell in view of Takigami. Claims 1-11 and 16-22 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Sherman in view of Takigami. Applicants respectfully request the allowance of the claims for the following reasons.

The present invention is directed to electronic components. Independent Claims 1 and 16 recite a semiconductor device including first lands electrically connected to second lands of a board, the second lands connected to wires. At least one of the second lands includes a primary land and an auxiliary land, the at least one second land connecting to at least one of the wires where a predetermined tensile stress is configured to be applied

between the at least one second land and the at least one wire. The primary land includes an arcuate shape. The auxiliary land includes a first portion disposed adjacent the primary land and a second portion connecting to the at least one wire, the first portion having a greater cross sectional area than the second portion. The at least one wire includes a via land, the via land having an arcuate portion electrically connected to a via hole. Independent Claim 17 recites a semiconductor device including at least one semiconductor land. A board includes at least one board land electrically connected to the at least one semiconductor land, the at least one board land including a primary portion contacting the at least one semiconductor land and an auxiliary portion electrically connected to a wire. The primary portion includes an arcuate shape. The auxiliary portion includes a first portion electrically connected to the primary portion and a second portion electrically connected to the wire, the first portion having a greater cross sectional area than the second portion. The wire includes a via land, the via land having an arcuate portion electrically connected to a via hole.

As discussed during the interview, Applicants respectfully assert that none of Howell, Sherman, and Takigami, whether taken alone or in combination, teaches or suggests the claimed features of a wire including a via land, the via land having an arcuate portion electrically connected to a via hole, as recited in independent Claims 1, 16, and 17.

Thus, Applicants respectfully assert that the claimed invention can provide numerous advantages that cannot be provided by a combination of Howell, Sherman, and Takigami. By way of specific non-limiting examples, Applicants respectfully assert that the claimed invention can provide a multilayer printed wiring board in which a connection between a wire and a via hole is prevented from breaking, even when a load is applied to the wiring board, such as during testing or assembly of the wiring board.<sup>1</sup>

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<sup>1</sup> From page 32, line 5 to page 18, of Applicants' originally filed specification.

Specifically, independent Claims 1 and 16 recite "the at least one wire comprises a via land, the via land including an arcuate portion electrically connected to a via hole," and independent Claim 17 recites "the wire comprises a via land, the via land including an arcuate portion electrically connected to a via hole." Thus, Applicants respectfully request that the rejections of independent Claims 1, 16, and 17 under 35 U.S.C. § 103(a) be withdrawn, and the allowance of independent Claims 1, 16, and 17.

Applicants respectfully assert that Claims 2-10 and 18-22 are allowable for the same reasons as the independent claims from which they depend, as well as for their own features. Thus, Applicants respectfully request the allowance of dependent Claims 2-10 and 18-22.

Consequently, in view of the present amendment, no further issues are believed to be outstanding in the present application, and the present application is believed to be in condition for formal Allowance. A Notice of Allowance for Claims 1-10 and 16-22 is earnestly solicited.

Should the Examiner deem that any further action is necessary to place this application in even better form for allowance, the Examiner is encouraged to contact the undersigned representative at the below listed telephone number.

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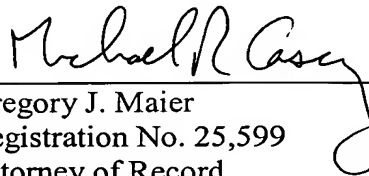
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Respectfully submitted,

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